

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-10 (Canceled)

Claim 11 (Currently Amended): A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and ~~[[a]]~~ water-soluble ~~particle~~ particles dispersed in the water-insoluble matrix material, wherein said water-soluble ~~particle~~ is particles are provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part.

Claim 12 (Currently Amended): The composition for a polishing pad according to claim 11, wherein said water-soluble ~~particle~~ particles ~~is an~~ are selected from the group consisting of (1) organic water-soluble ~~particle~~ particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, ~~and/or an~~ (2) inorganic water-soluble ~~particle~~ particles comprising at least one material selected from the group consisting of potassium acetate, potassium nitrate, potassium carbonate, potassium bicarbonate, potassium chloride, potassium bromide, potassium phosphate and magnesium nitrate, and (3) mixtures of (1) and (2).

Claim 13 (Original): The composition for a polishing pad according to claim 12, wherein the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

Claim 14 (Withdrawn; Currently Amended): A polishing pad characterized in that at least a part of said polishing pad comprises the composition of a water-insoluble matrix material containing a crosslinked polymer and ~~[[a]]~~ water-soluble ~~partiele~~ particles dispersed in the water-insoluble matrix material.

Claim 15 (Withdrawn): A polishing pad according to claim 14, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble matrix material is broken at 80°C.

Claim 16 (Withdrawn): A polishing pad according to claim 15, wherein the Shore D hardness is 35 or more.

Claim 17 (Currently Amended): A composition for a polishing pad which comprises a water-insoluble matrix material containing a crosslinked polymer and ~~[[an]]~~ organic water-soluble ~~partiele~~ particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-insoluble matrix material.

Claim 18 (Previously Presented): The composition for a polishing pad according to claim 17, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble matrix material is broken at 80°C.

Claim 19 (Previously Presented): The composition for a polishing pad according to claim 17, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

Claim 20 (Previously Presented): The composition for a polishing pad according to claim 17, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

Claim 21 (Previously Presented): The composition for a polishing pad according to claim 17, wherein the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

Claim 22 (Currently Amended): The composition for a polishing pad according to claim 17, wherein said water-soluble ~~particle is~~ particles are provided with an outer shell for inhibiting moisture absorption in an at least a part of the outermost part.

Claim 23 (Previously Presented): The composition for a polishing pad according to claim 22, wherein said outer shell is comprised of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

Claim 24 (Currently Amended): A composition for a polishing pad which comprises a water-insoluble matrix material containing a polymer crosslinked by an organic peroxide and ~~[[an]]~~ organic water-soluble ~~partiele~~ particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer dispersed in the water-insoluble matrix material.

Claim 25 (Previously Presented): The composition for a polishing pad according to claim 24, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

Claim 26 (Previously Presented): The composition for a polishing pad according to claim 24, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

Claim 27 (Previously Presented): The composition for a polishing pad according to claim 24, wherein the amount of said water-soluble particles is 10 to 90% by volume based

on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

Claim 28 (Currently Amended): The composition for a polishing pad according to claim 24, wherein said water-soluble ~~particle is~~ particles are provided with an outer shell for inhibiting moisture absorption in an at least a part of the outermost part.

Claim 29 (Currently Amended): ~~Composition~~ The composition for a polishing pad according to claim 28, wherein said outer shell is comprised of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

Claim 30 (Previously Presented): The composition for a polishing pad according to claim 11, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

Claim 31 (Previously Presented): The composition for a polishing pad according to claim 11, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

Claim 32 (Previously Presented): The composition for a polishing pad according to claim 11, wherein said outer shell is comprises of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

Claim 33 (New): The composition for a polishing pad according to claim 11, wherein said water-soluble particles have a particle size of 0.1 to 500 μm .

Claim 34 (New): The composition for a polishing pad according to claim 17, wherein said water-soluble particles have a particle size of 0.1 to 500 μm .

DISCUSSION OF THE AMENDMENT

The claims have been amended by changing from singular to plural form the water-soluble particles, as supported throughout the specification. In addition, Claim 12 has been amended by incorporating Markush terminology to clarify the Examiner's understanding that the water-soluble particles may be organic, inorganic, or a mixture of organic and inorganic such particles. New Claims 33 and 34 have been added, as supported in the specification at the sentence bridging pages 11 and 12.

No new matter has been added by the above amendment. Claims 11-13 and 17-34 are now active; Claims 14-16 stand withdrawn from consideration.